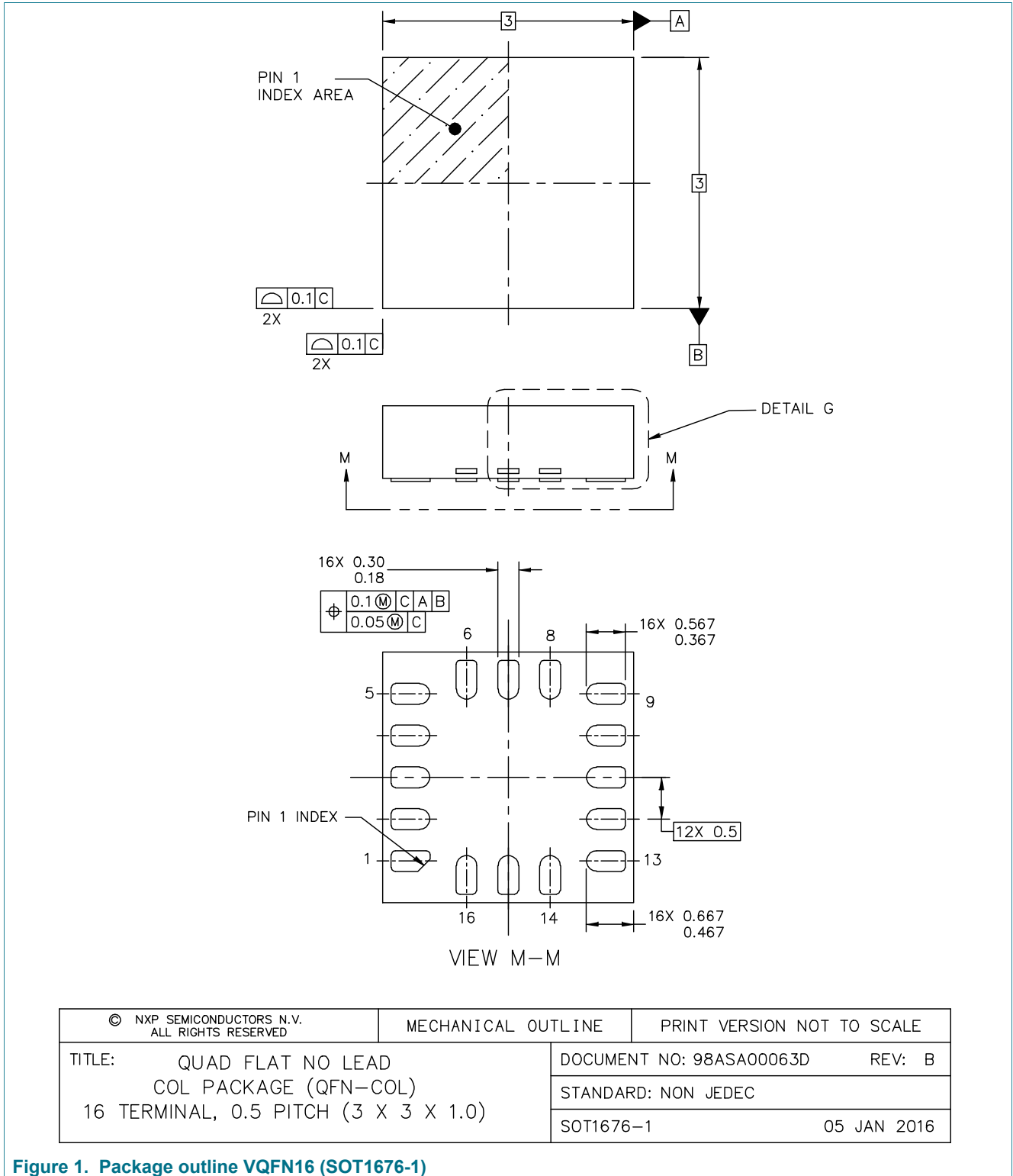# SOT1676-1

VQFN16, plastic, very thin quad flatpack; no leads; 16 terminals; 0.5 mm pitch; 3 mm x 3 mm x 1 mm body

18 August 2018

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	VQFN16
Package style descriptive code	VQFN (very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	05-01-2016
Manufacturer package code	98ASA00063D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	3	-	mm
package width	-	3	-	mm
package height	-	1	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	16	-	

2 Package outline

PIN 1
INDEX AREA

3

3

0.1 C
2X

0.1 C
2X

DETAIL G

M

M

16X 0.30
0.18

0.1 M C A B
0.05 M C

6   8

16X 0.567
0.367

5

9

12X 0.5

PIN 1 INDEX

1

13

16   14

16X 0.667
0.467

VIEW M−M

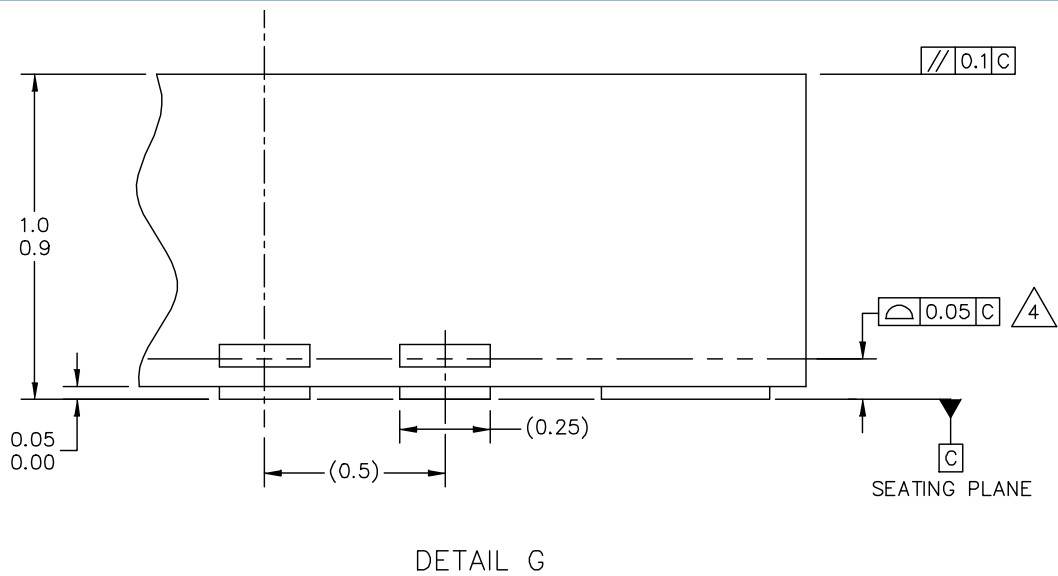| © NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: QUAD FLAT NO LEAD COL PACKAGE (QFN−COL) 16 TERMINAL, 0.5 PITCH (3 X 3 X 1.0)	DOCUMENT NO: 98ASA00063D REV: B	
	STANDARD: NON JEDEC	
	SOT1676−1 05 JAN 2016	

Figure 1. Package outline VQFN16 (SOT1676-1)

VQFN16, plastic, very thin quad flatpack; no leads; 16 terminals; 0.5 mm pitch; 3 mm x 3 mm x 1 mm body

DETAIL G

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TITLE: QUAD FLAT NO LEAD COL PACKAGE (QFN—COL) 16 TERMINAL, 0.5 PITCH (3 X 3 X 1.0)	DOCUMENT NO: 98ASA00063D	REV: B	
	STANDARD: NON JEDEC		
	SOT1676—1	05 JAN 2016	

Figure 2. Package outline detail of VQFN16 (SOT1676-1)

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.

2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M−1994.

3. THIS IS NON JEDEC REGISTERED PACKAGE.

4. COPLANARITY APPLIES TO ALL LEADS.

5. MIN. METAL GAP SHOULD BE 0.2MM.

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TITLE: QUAD FLAT NO LEAD COL PACKAGE (QFN−COL) 16 TERMINAL, 0.5 PITCH (3 X 3 X 1.0)	DOCUMENT NO: 98ASA00063D		REV: B
	STANDARD: NON JEDEC		
	SOT1676−1	05 JAN 2016	

Figure 3. Package outline note VQFN16 (SOT1676-1)

SOT1676-1

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Package information

18 August 2018

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3 Legal information

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